1 Characteristics

Table 2: Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			45	V
$I_{F(RMS)}$	Forward rms current			20	A
$I_{F(AV)}$	Average forward current δ = 0.5, square wave	T_C = 157 °C	Per diode	7.5	A
I_{FSM}	Surge non repetitive forward current	tp = 10 ms sinusoidal		150	A
P_{ARM}	Repetitive peak avalanche power	t_p = 10 µs, T_j = 125 °C		190	W
T_{stg}	Storage temperature range			-65 to + 175	°C
T_j	Maximum operating junction temperature (1)			+ 175	°C

Notes:

(1)$(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 3: Thermal parameters

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	3.0	°C/W
		Total	1.7	
$R_{th(c)}$	Coupling	-	0.35	°C/W

When the diodes 1 and 2 are used simultaneously:

$\Delta T_{j\ (diode1)} = P_{(diode1)} \times R_{th(j-c)}$ (per diode) + $P_{(diode2)} \times R_{th(c)}$

Table 4: Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R (1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RRM}$	-		100	µA
		T_j = 125 °C		-	5	15	mA
V_F (1)	Forward voltage drop	T_j = 125 °C	I_F = 7.5 A	-	0.5	0.57	V
		T_j = 25 °C	I_F = 15 A	-	-	0.84	
		T_j = 125 °C	I_F = 15 A	-	0.65	0.72	

Notes:

(1)Pulse test: t_p = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation:

$P = 0.42 \times I_{F(AV)} + 0.020\ I_{F^2(RMS)}$

1.1 Characteristics (curves)

Figure 1: Average forward power dissipation versus average forward current (per diode)

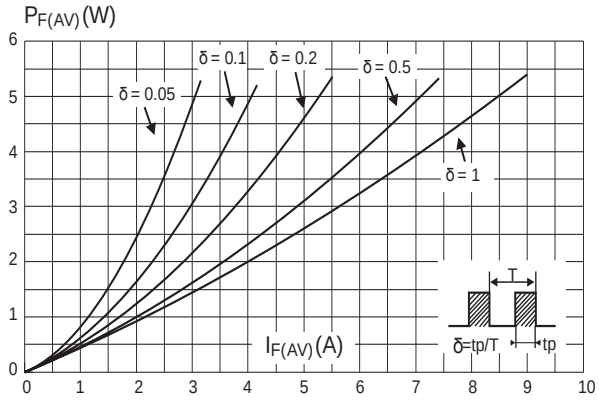


Figure 2: Average forward current versus ambient temperature (δ = 0.5, per diode)

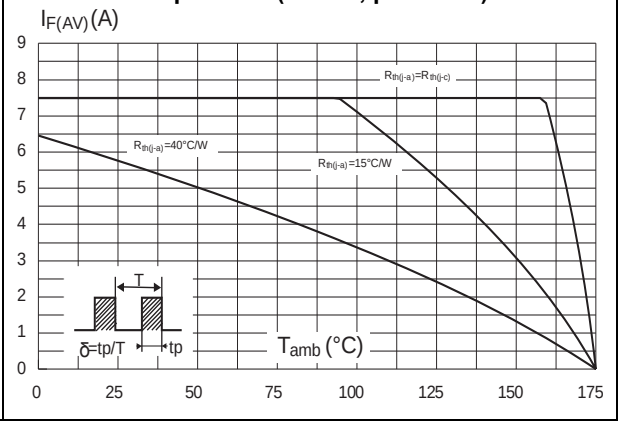


Figure 3: Normalized avalanche power derating versus pulse duration (Tj = 125 °C)

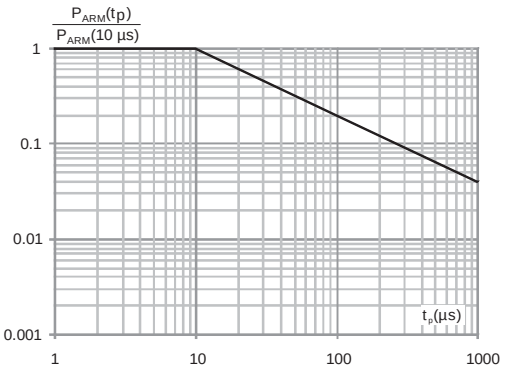


Figure 4: Relative variation of thermal impedance junction to case versus pulse duration

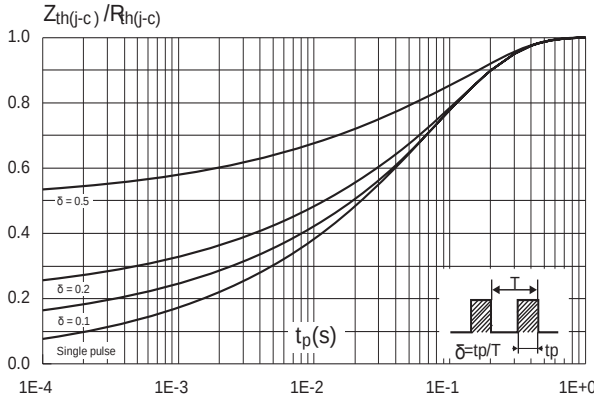


Figure 5: Reverse leakage current versus reverse voltage applied (typical values, per diode)

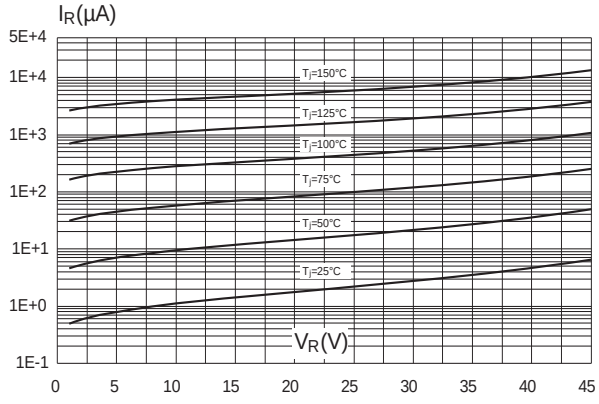


Figure 6: Junction capacitance versus reverse voltage applied (typical values, per diode)

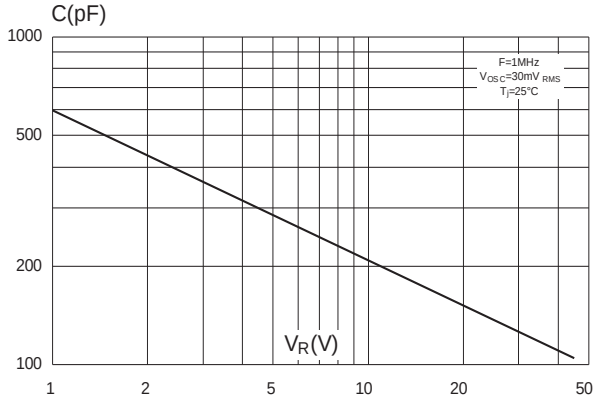


Figure 7: Forward voltage drop versus forward current (per diode)

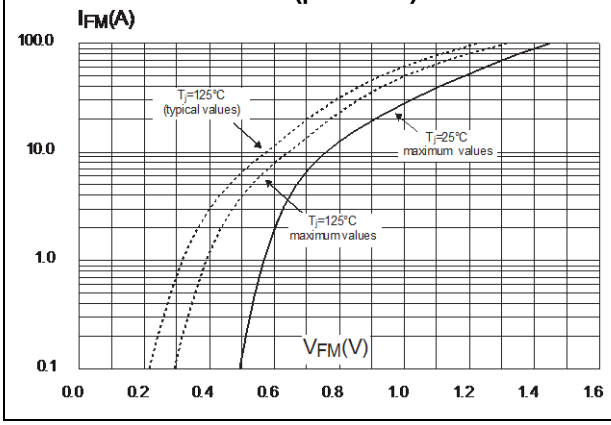
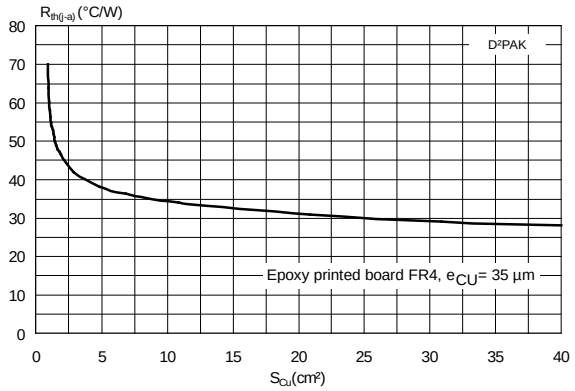


Figure 8: Thermal resistance junction to ambient versus copper surface under tab for D²PAK



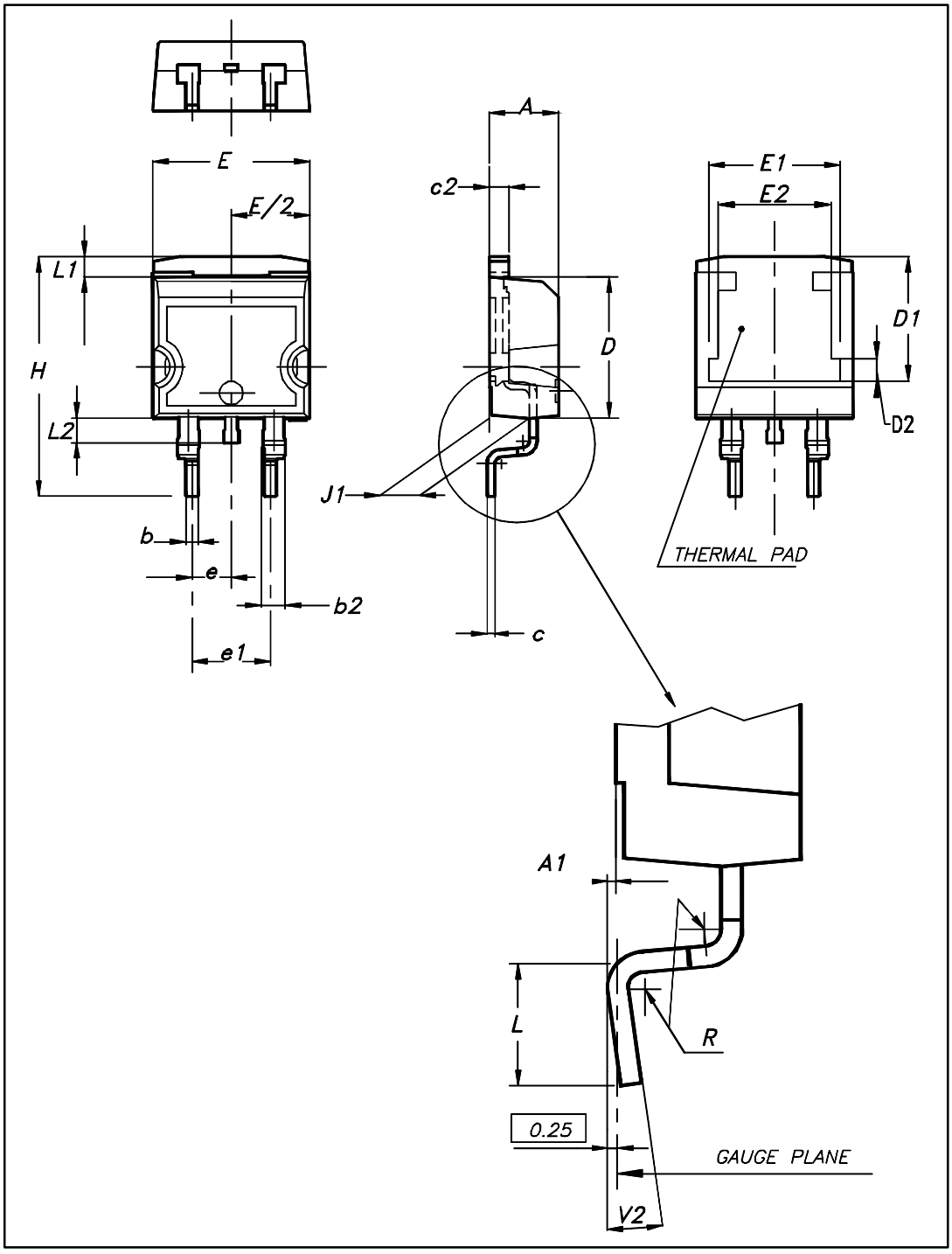
2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: ***www.st.com***. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0
- Recommended torque value: 0.55 N·m (for TO-220AB)
- Maximum torque value: 0.7 N·m (for TO-220AB)

2.1 D²PAK package information

Figure 9: D²PAK package outline

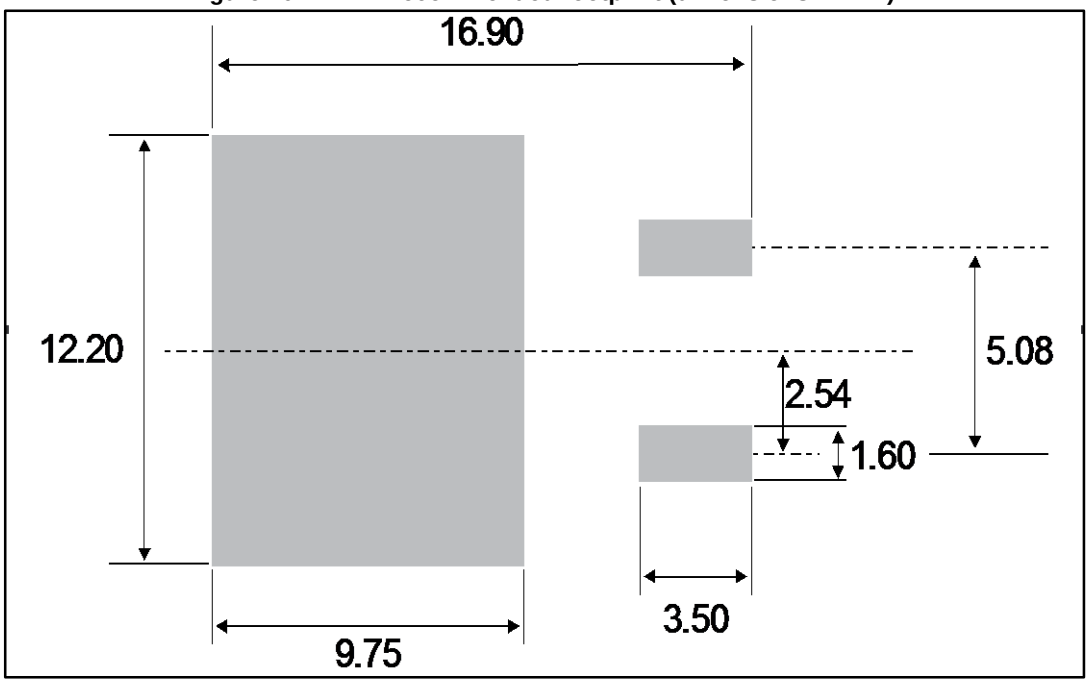


This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 5: D²PAK package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.36	4.60	0.172	0.181
A1	0.00	0.25	0.000	0.010
b	0.70	0.93	0.028	0.037
b2	1.14	1.70	0.045	0.067
c	0.38	0.69	0.015	0.027
c2	1.19	1.36	0.047	0.053
D	8.60	9.35	0.339	0.368
D1	6.90	8.00	0.272	0.311
D2	1.10	1.50	0.043	0.060
E	10.00	10.55	0.394	0.415
E1	8.10	8.90	0.319	0.346
E2	6.85	7.25	0.266	0.282
e	2.54 typ.		0.100	
e1	4.88	5.28	0.190	0.205
H	15.00	15.85	0.591	0.624
J1	2.49	2.90	0.097	0.112
L	1.90	2.79	0.075	0.110
L1	1.27	1.65	0.049	0.065
L2	1.30	1.78	0.050	0.070
R	0.4 typ.		0.015	
V2	0°	8°	0°	8°

Figure 10: D²PAK recommended footprint (dimensions in mm)



2.2 I²PAK package information

Figure 11: I²PAK package outline

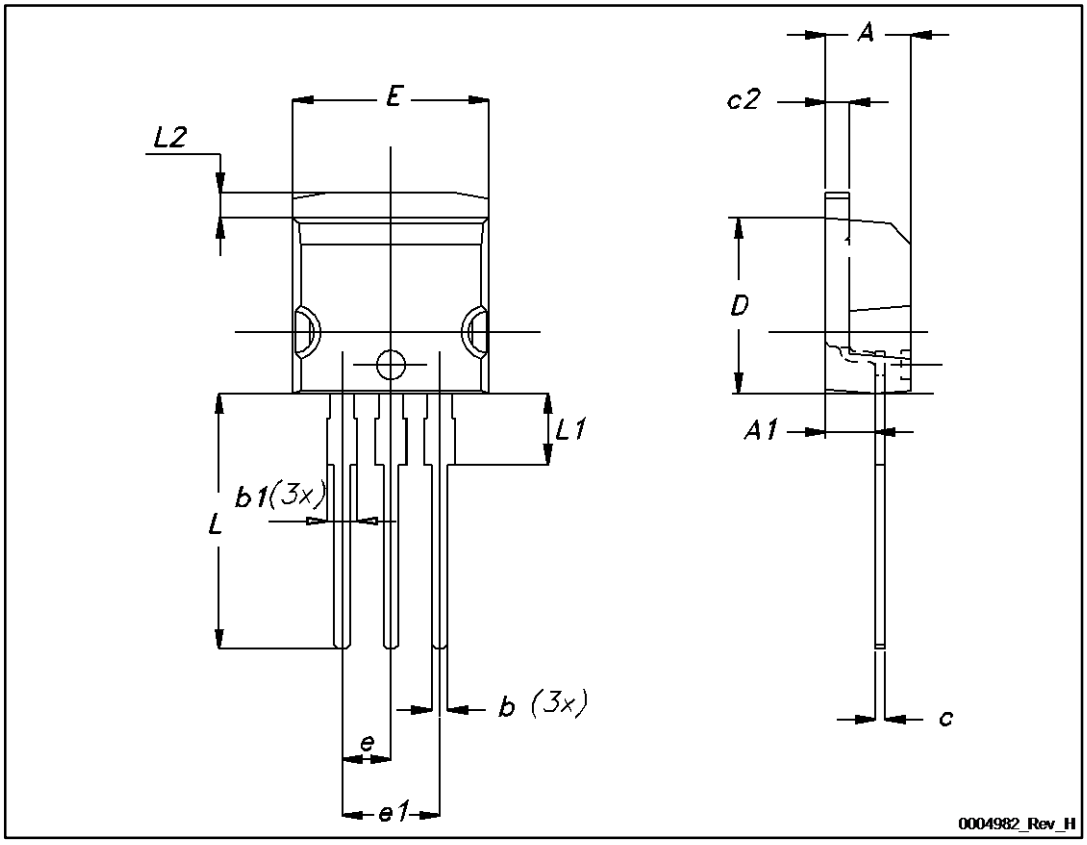


Table 6: I²PAK package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.40	0.72	0.094	0.107
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.044	0.067
c	0.49	0.70	0.019	0.028
c2	1.23	1.32	0.048	0.052
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
E	10.00	10.40	0.394	0.409
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L2	1.27	1.40	0.050	0.055

Mounting (soldering) the I²PAK metal slug (heatsink) with alloy, like a surface mount device, IS NOT PERMITTED. A standard through-hole mounting is mandatory.

2.3 TO-220AB package information

Figure 12: TO-220AB package outline

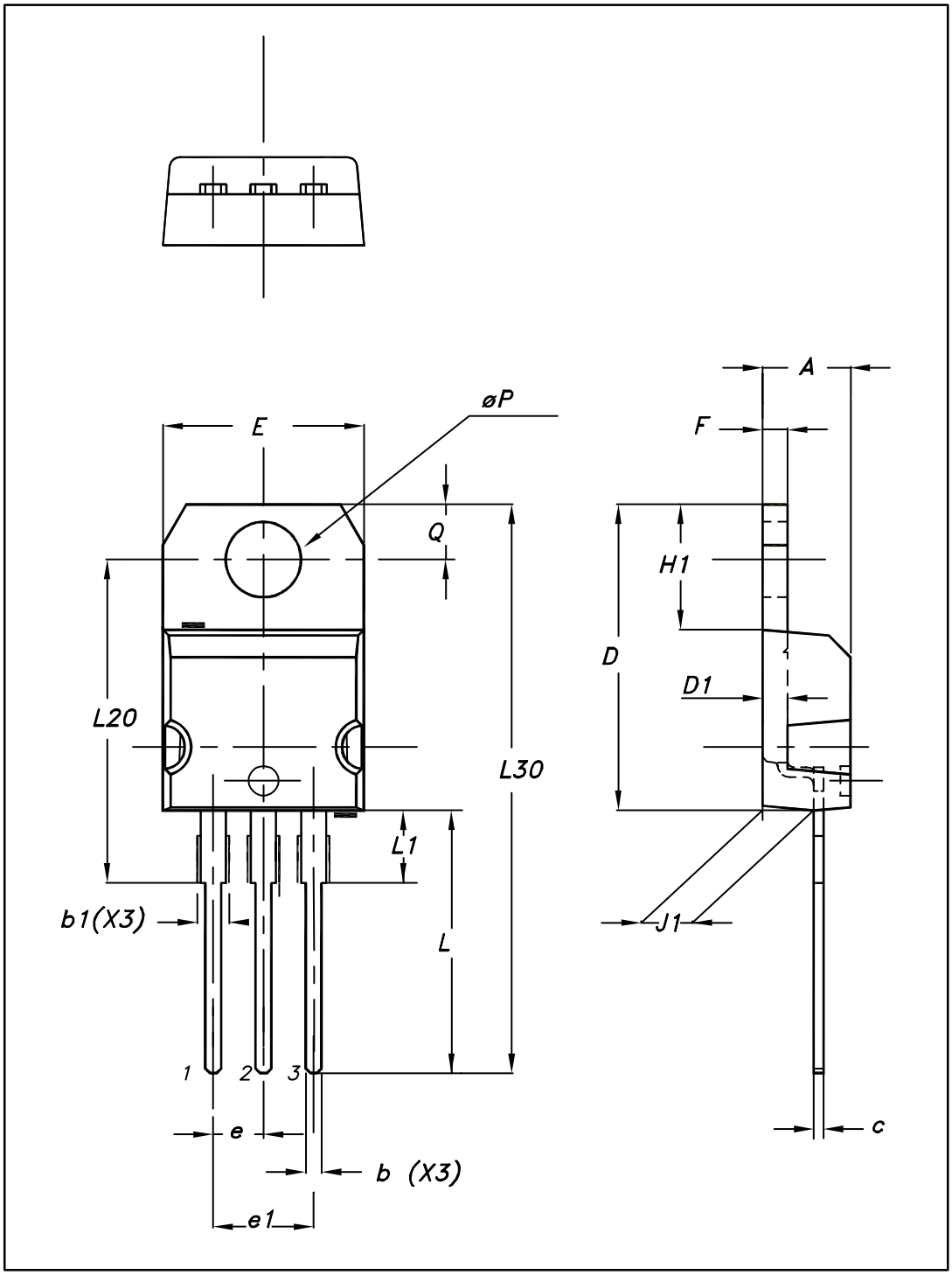


Table 7: TO-220AB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	0.61	0.88	0.240	0.035
b1	1.14	1.70	0.045	0.067
c	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
D1	1.27 typ.		0.050 typ.	
E	10.00	10.40	0.394	0.409
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.244	0.260
J1	2.40	2.72	0.094	0.107
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.646 typ.	
L30	28.90 typ.		1.138 typ.	
θP	3.75	3.85	0.148	0.152
Q	2.65	2.95	0.104	0.116

3 Ordering information

Table 8: Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS1545CT	STPS1545CT	TO-220AB	1.95g	50	Tube
STPS1545CR	STPS1545CR	I^2PAK	1.5g	50	Tube
STPS1545CG-TR	STPS1545CG	D^2PAK	1.38g	1000	Tape and reel

4 Revision history

Table 9: Document revision history

Date	Revision	Changes
Jul-2003	5F	Last release.
21-Mar-2007	6	Removed ISOWATT and TO-220FPAB packages.
03-Nov-2010	7	Added DPAK package
26-Feb-2016	8	Removed DPAK package. Updated features and packages silhouette in cover page. Updated *Section 1: "Characteristics"* and *Section 1.1: "Characteristics (curves)"*. Updated *Section 2.1: "D²PAK package information"*.

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